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NAKATANI SEIICHI**(54) **POWER MODULE AND ITS MANUFACTURING METHOD**

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(57) Abstract:

**PROBLEM TO BE SOLVED:** To provide a power module in which a heat generated by an electronic component is uniformly and efficiently radiated and which can be mounted in high density, and to provide a method for manufacturing the same.

**SOLUTION:** The power module comprises a circuit board (103) in which a heating component (101) is electrically connected and which is connected to a heat sink (105) via a heat conductive electric insulating member (104). In this module, the insulating member (104) is a curable composition containing a thermosetting resin (A), a thermoplastic resin (B), a latent curing agent (C), and an inorganic filler (D). The insulating member is adhered to the heating component in a state in which the member is complementarily deformed to unevennesses of a shape of the heating component and a component height. A heat generated by the component (101) is radiated by the heat sink (105).

